

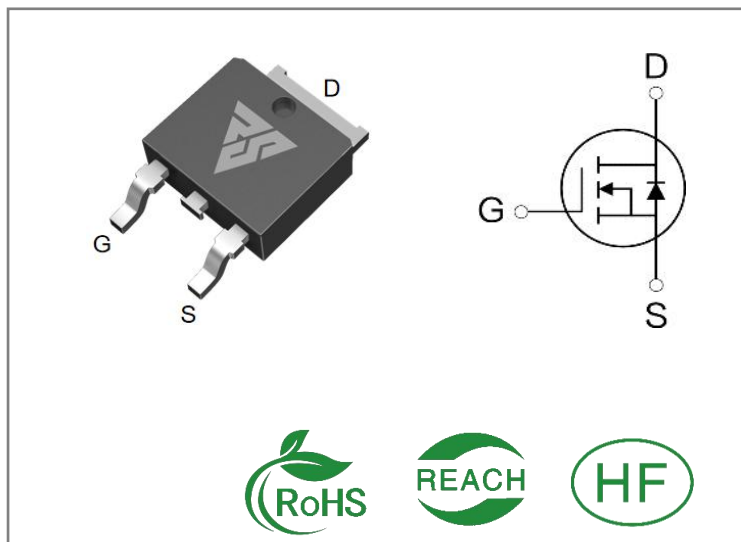
ID	$R_{DS(ON)}$ (Typ)	VDSS
11A	340m Ω	650V

Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC-DC Switching Power Supply

Features:

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability



Ordering Information

Part Number	Package	Marking	Packing	Qty.
RS65R380D	T0-252	RS65R380D	Tape&reel	2500 PCS

Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	RS65R380D	Units
VDSS	Drain-to-Source Voltage	650	V
ID	Continuous Drain Current $T_C = 25^\circ\text{C}$	11	A
ID	Continuous Drain Current $T_C = 100^\circ\text{C}$	7	
IDM	Pulsed Drain Current (Note*1)	33	
PD	Power Dissipation	118	W
VGS	Gate- to- Source Voltage	± 30	V
EAS	Single Pulse Avalanche Energy $L = 10\text{mH}, V_{DS} = 50\text{V}, R_G = 25\ \Omega, T_C = 25^\circ\text{C}$	210	mJ
dv/dt	MOSFET dv/ dt ruggedness $V_{DS} = 0 \dots 400\text{V}$	50	V/ns
dv/dt	Reverse diode dv/dt $V_{DS} = 0 \dots 400\text{V}, T_j = 25^\circ\text{C}, I_{SD} \leq I_D$	15	V/ns
TL TPKG	Maximum Temperature for Soldering	300 260	$^\circ\text{C}$
	Leads at 0.063in(1.6mm)from Case for 10 seconds		
	Package Body for 10 seconds		
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the " Absolute Maximum Ratings" Table may cause permanent damage to the device.

Thermal Resistance

Symbol	Parameter	RS65R380D	Units	Test Conditions
R θ JC	Junction-to-Case	1.32	$^{\circ}\text{C} / \text{W}$	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 1 5 0 $^{\circ}\text{C}$
R θ JA	Junction-to-Ambient	87		1 cubic foot chamber, free air.

OFF Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	650	--	--	V	VGS=0V, ID=250 μ A
IDSS	Drain- to- Source Leakage Current	--	--	1	μ A	VDS=650V, VGS=0V
IGSS	Gate- to- Source Forward Leakage	--	--	100	nA	VGS=30V, VDS=0V
	Gate- to- Source Reverse Leakage	--	--	-100		VGS=-30V, VDS=0V

ON Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On-Resistance(Note*2)	--	340	380	m Ω	VGS=10V, ID=5.5A
VGS(TH)	Gate Threshold Voltage	2	--	4	V	VGS=VDS, ID=250 μ A

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time	--	16.3	--	nS	VDS=400V ID=5.5A RG=25 Ω
trise	Rise Time	--	35	--		
td(OFF)	Turn- OFF Delay Time	--	78	--		
tfall	Fall Time	--	39.5	--		

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Ciss	Input Capacitance	--	852	--	pF	VGS=0V VDS=100V f=1.0MHz
Coss	Output Capacitance	--	37	--		
Crss	Reverse Transfer Capacitance	--	2	--		
Qg	Total Gate Charge	--	19.2	--	nC	VDS=520V ID=5.5A VGS=10V
Qgs	Gate- to- Source Charge	--	3.1	--		
Qgd	Gate-to-Drain(" Miller") Charge	--	8.2	--		

Source- Drain Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current	--	--	11	A	Integral pn- diode in MOSFET
ISM	Maximum Pulsed Current	--	--	33	A	
VSD	Diode Forward Voltage	--	0.85	--	V	IS=5.5A,VGS=0V
trr	Reverse Recovery Time	--	310	--	nS	VR=100V IS=5.5A,di/dt=10 0A/μs
Qrr	Reverse Recovery Charge	--	2.8	--	μC	

Notes:

- * 1. Repetitive rating, pulse width limited by maximum junction temperature.
- * 2. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Typical Feature Curve

Figure 1. Output Characteristics

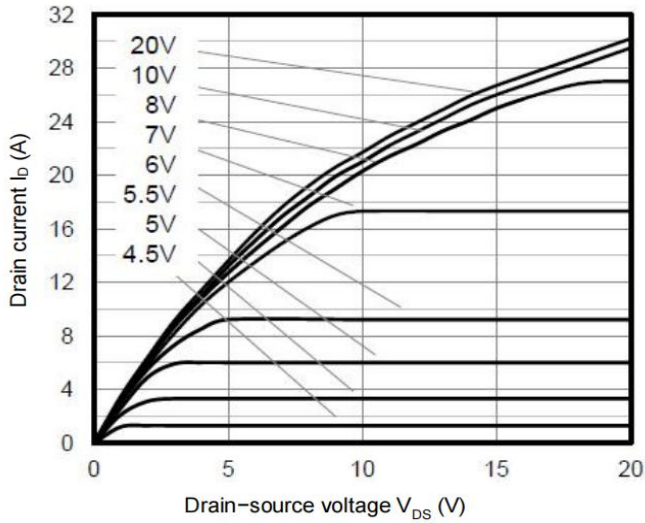


Figure 2. Transfer Characteristics

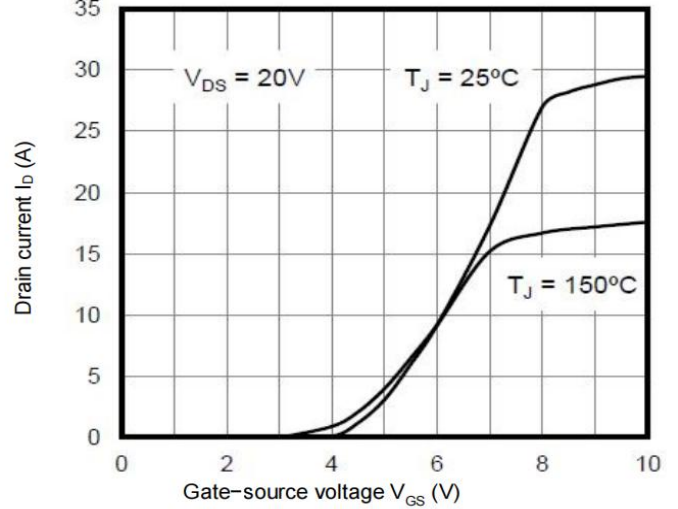


Figure 3. On-Resistance vs. Drain Current

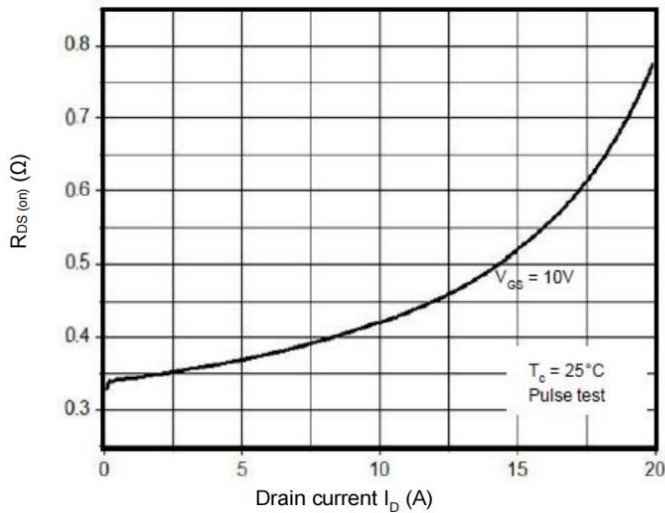


Figure 4. Capacitance Characteristics

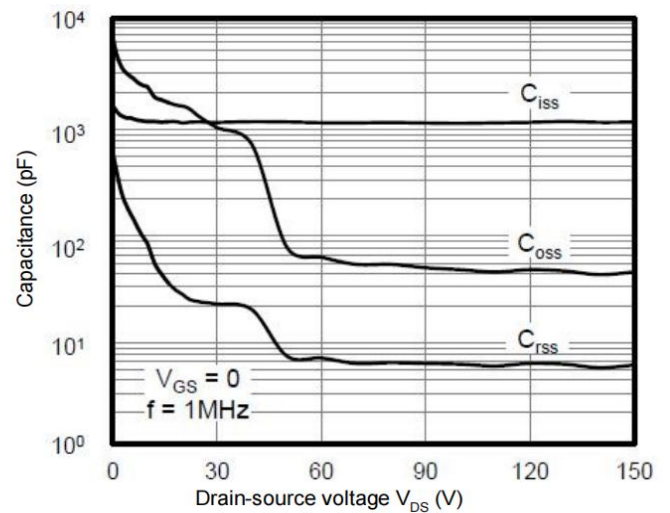


Figure 5. Gate Charge Characteristics

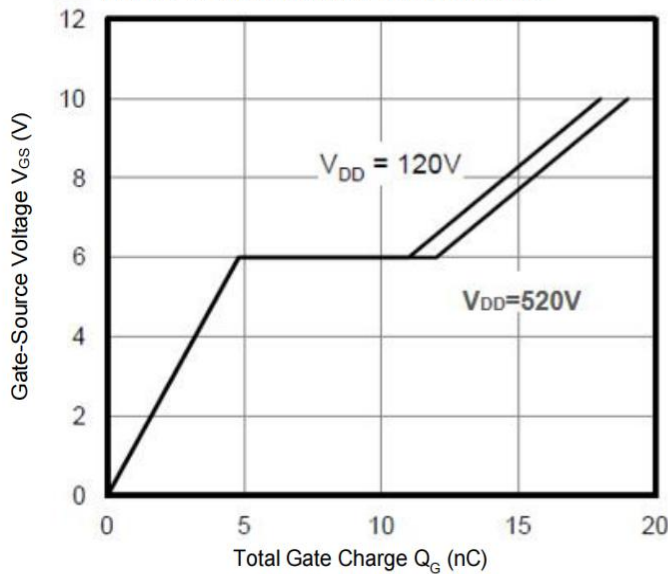


Figure 6. Body Diode Forward Voltage

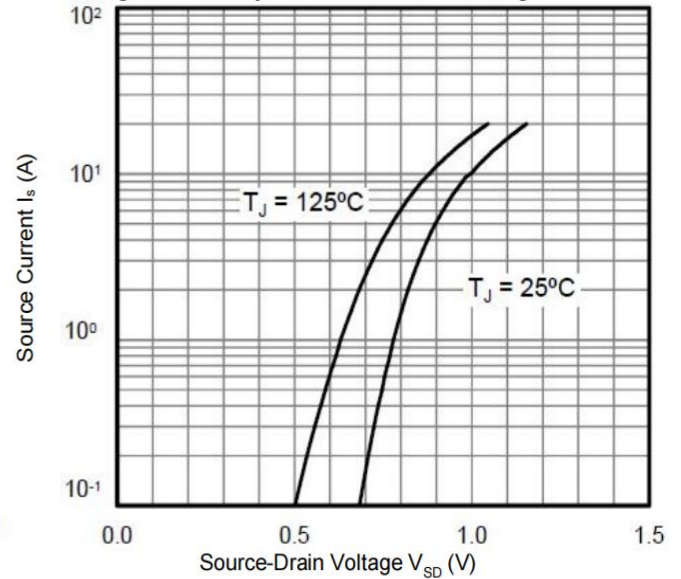


Figure 7. Breakdown Voltage vs. Temperature

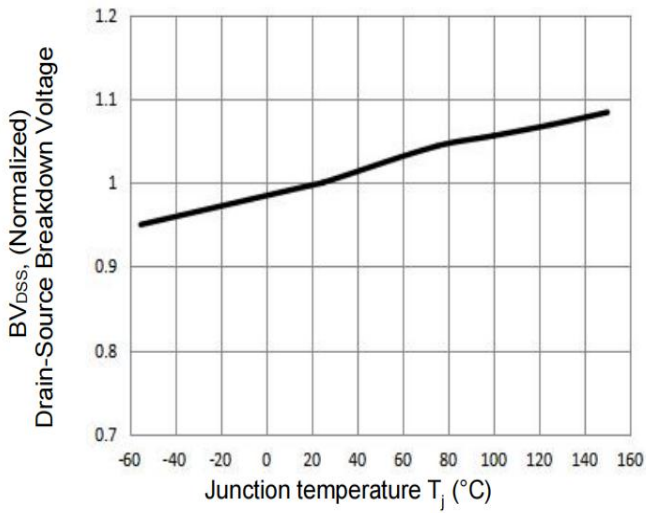


Figure 8. On-Resistance vs. Temperature

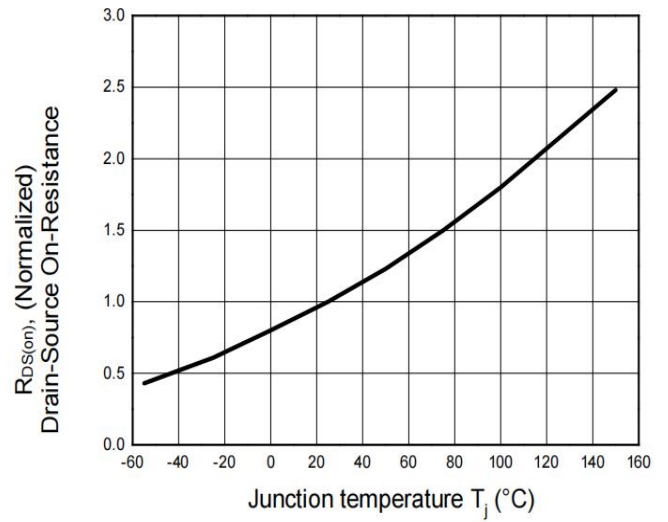
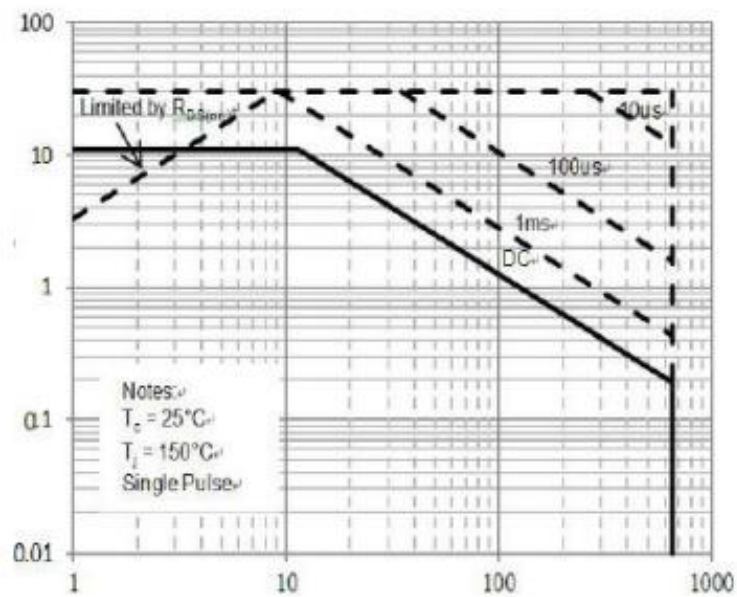


Figure9. MaximumSafeOperatingArea



Test Circuits and Waveforms

Figure A: Gate Charge Test Circuit and Waveform

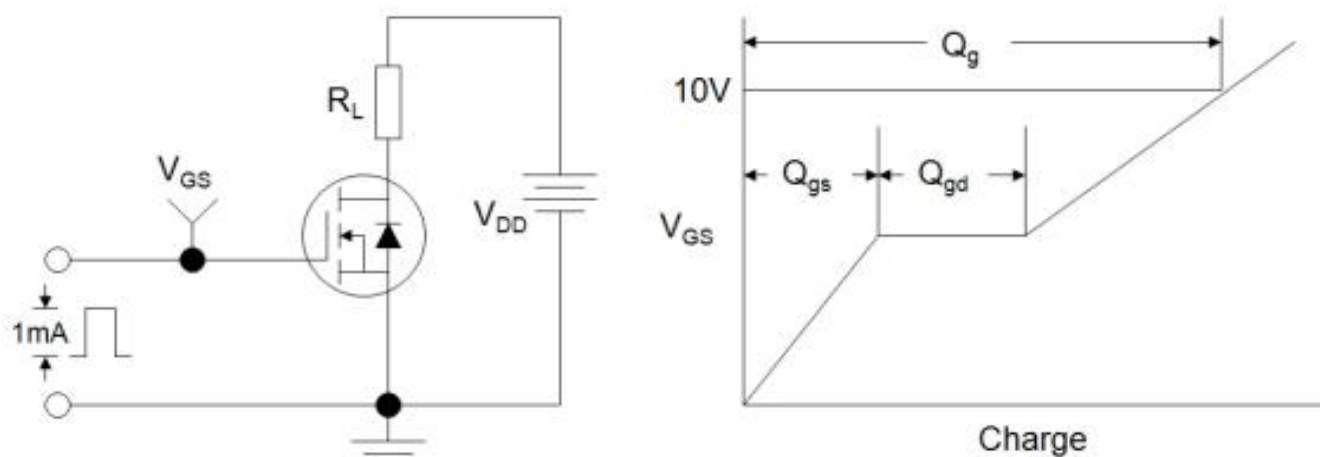


Figure B: Resistive Switching Test Circuit and Waveform

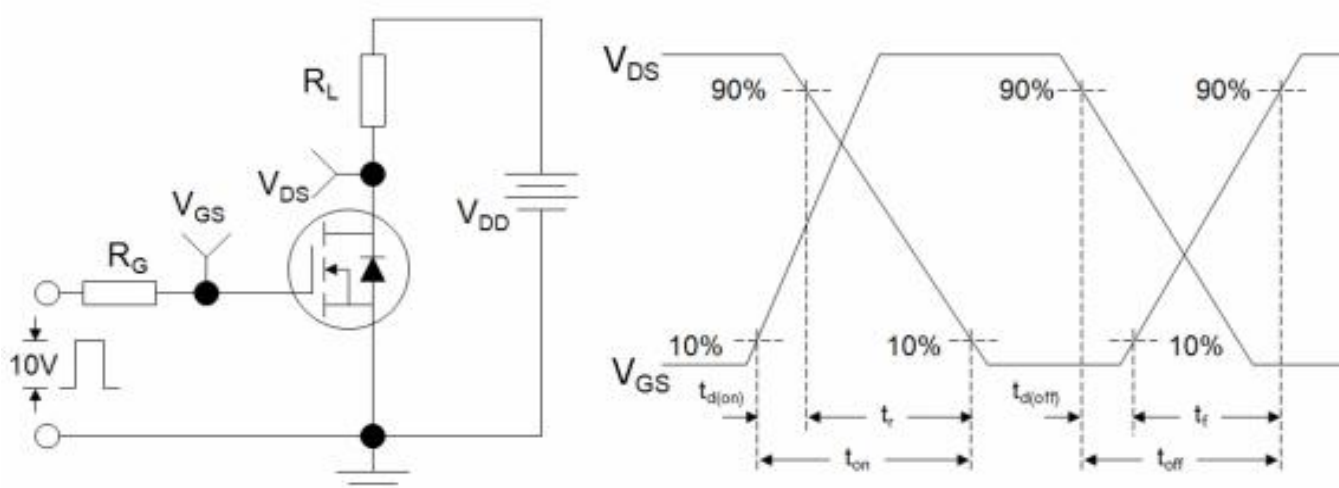
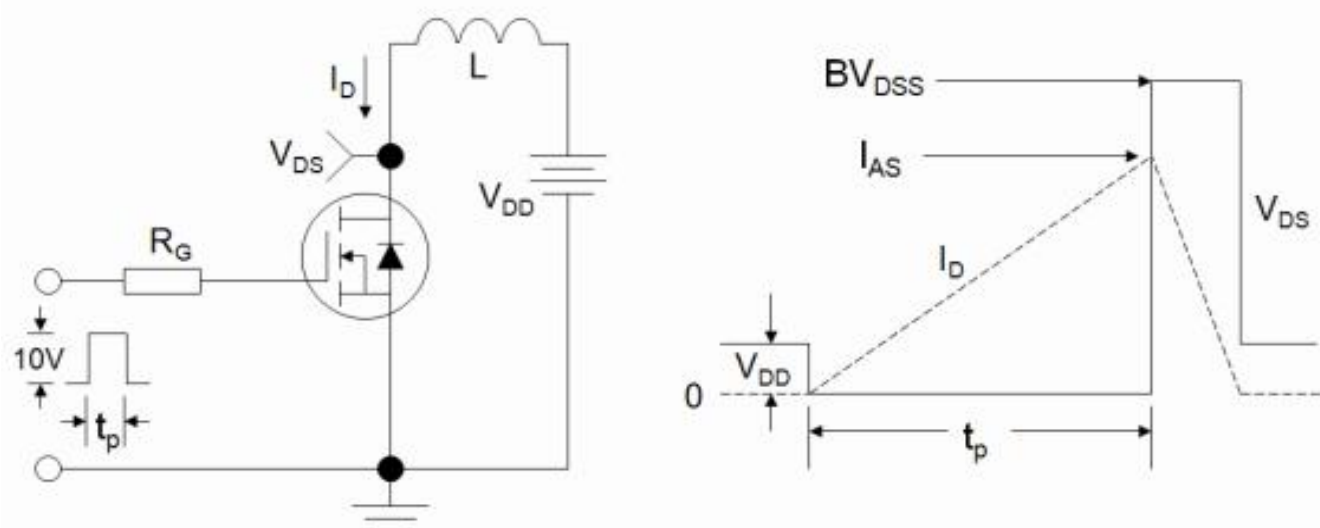
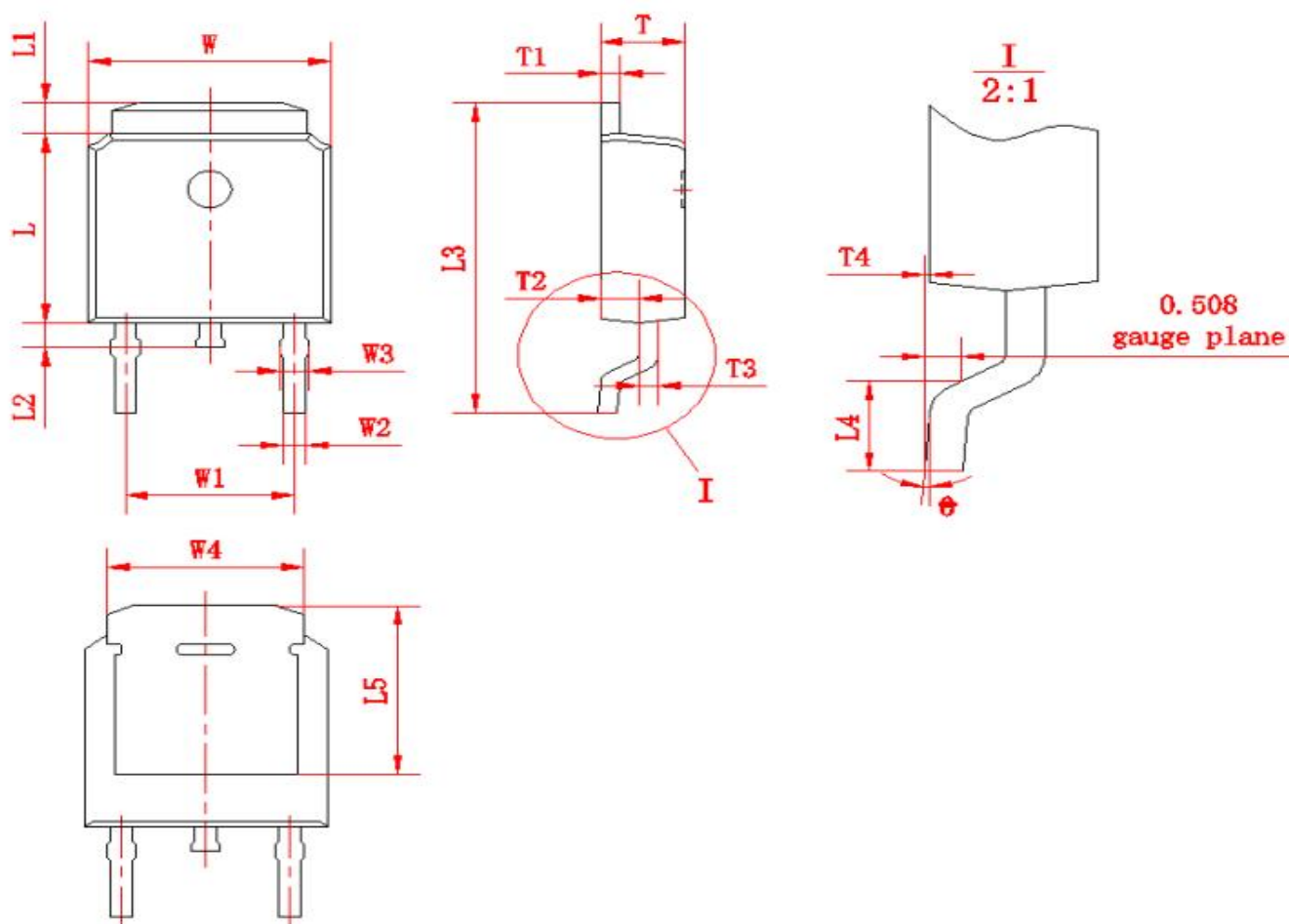


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



Package outline drawing(TO-252 Unit: mm)


符号	尺寸		符号	尺寸		符号	尺寸	
	Min	Max		Min	Max		Min	Max
W	6.50	6.70	L1	0.80	1.20	T1	0.48	0.58
W1	(4.572)		L2	0.60	1.00	T2	0.95	1.15
W2	0.6	0.8	L3	9.70	10.30	T3	0.48	0.58
W3	0.68	0.88	L4	1.30	1.70	T4	0.00	0.12
W4	(5.3)		L5	(5.20)		0	0	8
L	6.00	6.20	T	2.20	2.40			

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